

PCN Number: Date Issued:	PCN 20005	Means of Distinguishing Changed Devices:
Product(s) Affected:	SP337EBEY-L SP337EBEY-L/TR	Product Mark: Back Mark Date Code
Manufacturing Locati	on Affected: TSMC Fab 10   Shangh	oi Other
Date Effective (90 day	window): June 18, 2020	
Date Issued +90 days:	September 18, 2020	
Customer Si	MaxLinear Marketing Representative of upport team by creating a Support Tion maxlinear.com/support/createcase	
Phone: 1-760-692-0	711	Representatives
Description and Purpose of Change:  MaxLinear has qualified TSMC Fab 10 wafer foundry in Shanghai in order to facilitate long term support of the product line. The wafer process is 0.25um		- I I ACCOMNIV PROCACC
CMOS High Voltage Mixed Signal.  There are no changes to form, fit, or function		☐ Material
•	ly location, package BOM, device reli	Testing  Manufacturing Site
Note: Users who rely on DC, diode characteristics during ICT testing should take caution certain I/O characteristics may appear changed due to the proprietary I/O structures employed by TSMC. These DC / diode characteristic differences are not guaranteed nor required to ensure full design functionality per datasheet. Adjustments at ICT testing may be required to prevent false failures.		T testing should did due to the diode to ensure full
Reliability/Qualification	on Summary: Available upon request	
Customer Acknowled acceptance of change		ssue. Lack of acknowledgement within 30 days constitutes
Please fax or email th	is form to the contact above after co	npleting the following information:
Customer:		
Name:		
Title:		
	·	
Date.		
E-Mail:		
E-Mail:		
E-Mail:		
E-Mail: Phone: Fax:		